

DDR4 DIMM

TE Internal #: 8-2199154-8

TE Internal Description: DDR4 DIMM 288 Pin TH type

DDR4 DIMM SOCKETS

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Connectors > Socket Connectors > Memory Sockets > DIMM Sockets > DDR4 DIMM SOCKETS



DRAM Type: Double Data Rate (DDR) 4

Connector System: Board-to-Board

Number of Positions: 288

Termination Method to PCB: Through Hole - Solder

Module Orientation: Vertical

[All DDR4 DIMM SOCKETS \(25\)](#)

Features

Electrical Characteristics

| | |
|--------------|-------|
| DRAM Voltage | 1.2 V |
|--------------|-------|

Operation/Application

| | |
|---------------------|--------|
| Circuit Application | Signal |
|---------------------|--------|

Industry Standards

| | |
|------------------------|----------|
| UL Flammability Rating | UL 94V-0 |
|------------------------|----------|

Mechanical Attachment

| | |
|--------------------------|--------------|
| Connector Mounting Type | Board Mount |
| PCB Mount Retention | With |
| Mount Angle | Vertical |
| PCB Mount Retention Type | Boardlock |
| Mating Alignment Type | Offset Right |
| Mating Alignment | With |

Contact Features

| | |
|--|----------------|
| Contact Underplating Material | Nickel |
| Socket Style | DIMM |
| Contact Mating Area Plating Material Thickness | .38 µm[15 µin] |

| | |
|---|---|
| PCB Contact Termination Area Plating Material Thickness | 3 μm [118.1 μin] |
| Contact Mating Area Plating Material | Gold |
| Memory Socket Type | Memory Card |
| Contact Base Material | Copper Alloy |
| PCB Contact Termination Area Plating Material | Tin |
| Contact Current Rating (Max) | .75 A |

Packaging Features

| | |
|--------------------|------------------|
| Packaging Quantity | 80 |
| Packaging Method | Tray, Box & Tray |

Body Features

| | |
|--------------------------------|--------------------------------|
| Retention Post Location | None |
| Latch Color | Black |
| Latch Material | High Temperature Thermoplastic |
| PCB Retention Feature Material | Stainless Steel |
| Ejector Material Color | Natural |
| Module Key Type | Offset Right |
| Ejector Location | Both Ends |
| Ejector Material | High Temperature Thermoplastic |
| Ejector Type | Standard |

Dimensions

| | |
|--------------------------------|-----------------|
| Center Retention Hole Diameter | 1.2 mm[.047 in] |
| Profile Height from PCB | 20 mm[.787 in] |
| Row-to-Row Spacing | 2.2 mm[.08 in] |

Housing Features

| | |
|--------------------|------------------------|
| Housing Color | Blue |
| Housing Material | High Temperature Nylon |
| Centerline (Pitch) | .85 mm[.033 in] |

Termination Features

| | |
|--------------------------------|-----------------------|
| Insertion Style | Direct Insert |
| Termination Post & Tail Length | 2.67 mm[.105 in] |
| Termination Method to PCB | Through Hole - Solder |

Configuration Features

| | |
|---------------------|----------|
| Number of Keys | 1 |
| Number of Bays | 2 |
| Number of Rows | 2 |
| Number of Positions | 288 |
| Module Orientation | Vertical |

Product Type Features

| | |
|-----------------------------------|--------------------------|
| Connector & Contact Terminates To | Printed Circuit Board |
| DRAM Type | Double Data Rate (DDR) 4 |
| Connector System | Board-to-Board |

Usage Conditions

| | |
|-----------------------------|-----------------------------|
| Operating Temperature Range | -55 – 105 °C [-67 – 221 °F] |
|-----------------------------|-----------------------------|

Other

| | |
|--------------------|-----------|
| EU RoHS Compliance | Compliant |
|--------------------|-----------|

Product Compliance

For compliance documentation, visit the product page on TE.com>

| | |
|---|--|
| EU RoHS Directive 2011/65/EU | Compliant |
| EU ELV Directive 2000/53/EC | Not Yet Reviewed |
| China RoHS 2 Directive MIIT Order No 32, 2016 | No Restricted Materials Above Threshold |
| EU REACH Regulation (EC) No. 1907/2006 | Current ECHA Candidate List: JUNE 2024 (241) Candidate List Declared Against: JUL 2019 (201) Does not contain REACH SVHC |
| Halogen Content | Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free |
| Solder Process Capability | Wave solder capable to 260°C |

Product Compliance Disclaimer

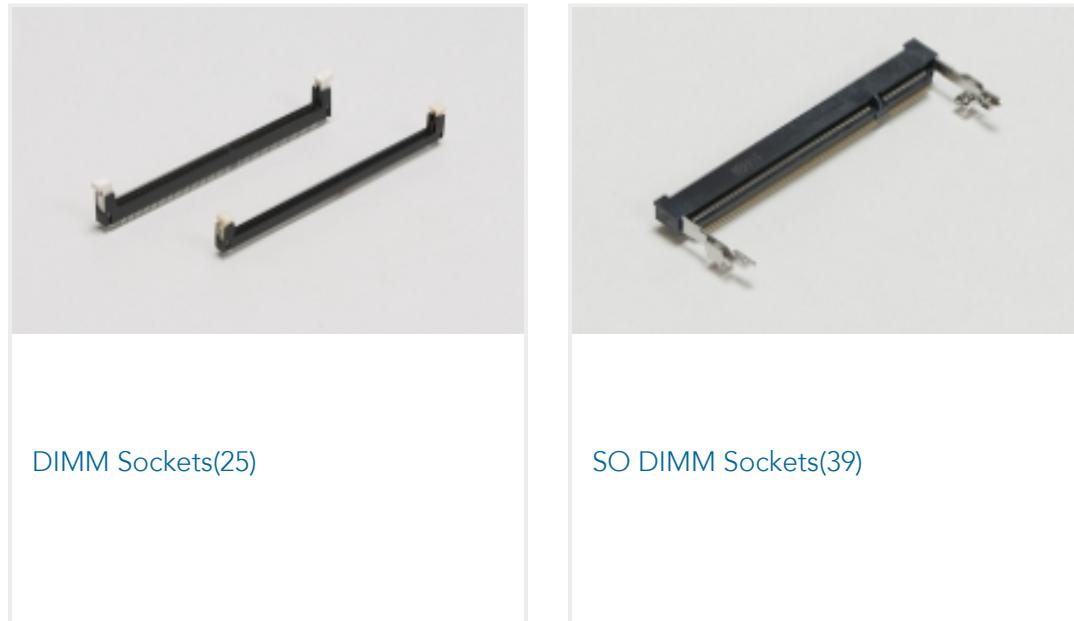
This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on

requirements for substances in articles' posted at this URL: <https://echa.europa.eu/guidance-documents/guidance-on-reach>

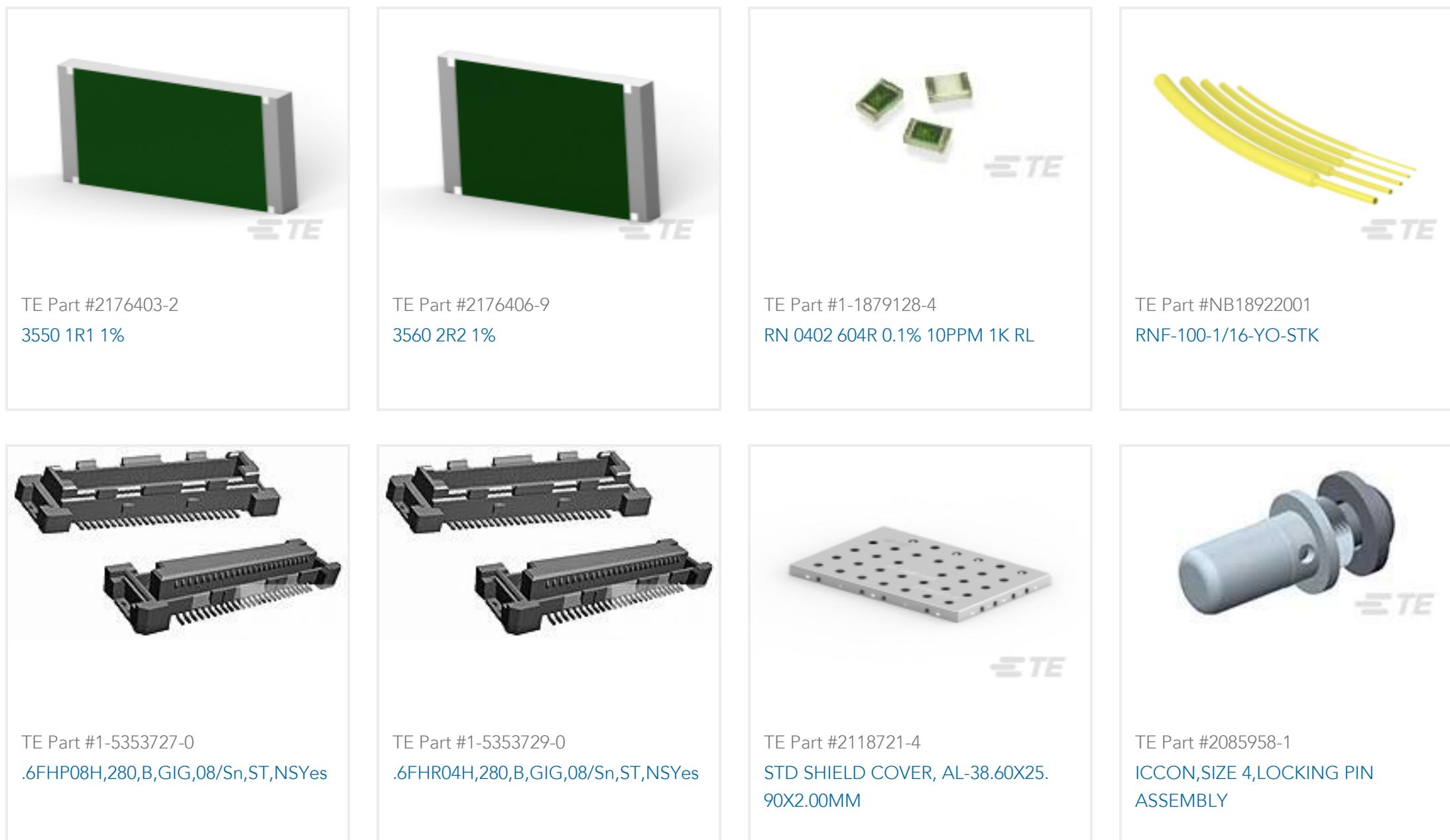
Compatible Parts



Also in the Series | DDR4 DIMM



Customers Also Bought





TE Part #5-535512-2
112 MODII HORZ DR CE EESS .100

Documents

Product Drawings

DDR4 DIMM 288 Pin TH type

English

CAD Files

3D PDF

3D

Customer View Model

[ENG_CVM_CVM_8-2199154-8_C5.2d_dxf.zip](#)

English

Customer View Model

[ENG_CVM_CVM_8-2199154-8_C5.3d_stp.zip](#)

English

Customer View Model

[ENG_CVM_CVM_8-2199154-8_C5.3d_igs.zip](#)

English

By downloading the CAD file I accept and agree to the [Terms and Conditions](#) of use.

Datasheets & Catalog Pages

DDR4 DIMM Socket Flyer (English)

English

DDR4 DIMM Socket Flyer (Chinese)

Product Specifications

Application Specification

English